

STARPOWER

SEMICONDUCTOR

IGBT

GD650HFL170P1S

1700V/650A 2 in one-package

General Description

STARPOWER IGBT Power Module provides ultra low conduction loss as well as short circuit ruggedness. They are designed for the applications such as wind and solar power.

Features

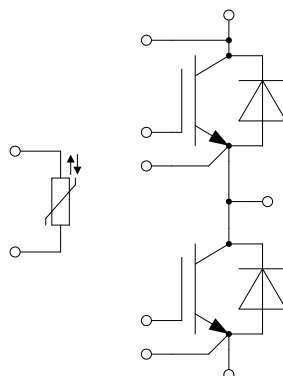
- Low $V_{CE(sat)}$ SPT+ IGBT technology
- 10 μ s short circuit capability
- $V_{CE(sat)}$ with positive temperature coefficient
- Maximum junction temperature 175°C
- Enlarged Diode for regenerative operation
- Isolated copper baseplate using DBC technology
- High power and thermal cycling capability



Typical Applications

- High Power Converter
- Wind and Solar Power
- Traction Drive

Equivalent Circuit Schematic



Absolute Maximum Ratings $T_C=25^{\circ}\text{C}$ unless otherwise noted**IGBT**

Symbol	Description	Value	Unit
V_{CES}	Collector-Emitter Voltage	1700	V
V_{GES}	Gate-Emitter Voltage	± 20	V
I_C	Collector Current @ $T_C=25^{\circ}\text{C}$	1147	A
	@ $T_C=100^{\circ}\text{C}$	650	A
I_{CM}	Pulsed Collector Current $t_p=1\text{ms}$	1300	A
P_D	Maximum Power Dissipation @ $T_j=175^{\circ}\text{C}$	4.3	kW

Diode

Symbol	Description	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	1700	V
I_F	Diode Continuous Forward Current	650	A
I_{FM}	Diode Maximum Forward Current $t_p=1\text{ms}$	1300	A

Module

Symbol	Description	Value	Unit
T_{jmax}	Maximum Junction Temperature	175	$^{\circ}\text{C}$
T_{jop}	Operating Junction Temperature	-40 to +150	$^{\circ}\text{C}$
T_{STG}	Storage Temperature Range	-40 to +150	$^{\circ}\text{C}$
V_{ISO}	Isolation Voltage RMS, $f=50\text{Hz}$, $t=1\text{min}$	4000	V

IGBT Characteristics $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit	
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=650\text{A}, V_{GE}=15\text{V}, T_j=25^\circ\text{C}$		2.00	2.45	V	
		$I_C=650\text{A}, V_{GE}=15\text{V}, T_j=125^\circ\text{C}$		2.40			
		$I_C=650\text{A}, V_{GE}=15\text{V}, T_j=150^\circ\text{C}$		2.50			
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=24.0\text{mA}, V_{CE}=V_{GE}, T_j=25^\circ\text{C}$	5.4	6.2	7.4	V	
I_{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0\text{V}, T_j=25^\circ\text{C}$			5.0	mA	
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0\text{V}, T_j=25^\circ\text{C}$			400	nA	
R_{Gint}	Internal Gate Resistance			2.3		Ω	
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}, f=1\text{MHz}, V_{GE}=0\text{V}$		40.5		nF	
C_{res}	Reverse Transfer Capacitance				1.38		nF
Q_G	Gate Charge	$V_{GE}=-15\dots+15\text{V}$		4.62		μC	
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=900\text{V}, I_C=650\text{A}, R_{Gon}=1.8\Omega, R_{Goff}=2.7\Omega, V_{GE}=\pm 15\text{V}, T_j=25^\circ\text{C}$		549		ns	
t_r	Rise Time			91		ns	
$t_{d(off)}$	Turn-Off Delay Time			1000		ns	
t_f	Fall Time			290		ns	
E_{on}	Turn-On Switching Loss			204		mJ	
E_{off}	Turn-Off Switching Loss			141		mJ	
$t_{d(on)}$	Turn-On Delay Time		$V_{CC}=900\text{V}, I_C=650\text{A}, R_{Gon}=1.8\Omega, R_{Goff}=2.7\Omega, V_{GE}=\pm 15\text{V}, T_j=125^\circ\text{C}$		601		ns
t_r	Rise Time				109		ns
$t_{d(off)}$	Turn-Off Delay Time			1250		ns	
t_f	Fall Time			490		ns	
E_{on}	Turn-On Switching Loss			301		mJ	
E_{off}	Turn-Off Switching Loss			204		mJ	
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=900\text{V}, I_C=650\text{A}, R_{Gon}=1.8\Omega, R_{Goff}=2.7\Omega, V_{GE}=\pm 15\text{V}, T_j=150^\circ\text{C}$			601		ns
t_r	Rise Time				119		ns
$t_{d(off)}$	Turn-Off Delay Time			1300		ns	
t_f	Fall Time			570		ns	
E_{on}	Turn-On Switching Loss			321		mJ	
E_{off}	Turn-Off Switching Loss			229		mJ	
I_{SC}	SC Data		$t_p \leq 10\mu\text{s}, V_{GE}=15\text{V}, T_j=150^\circ\text{C}, V_{CC}=1000\text{V}, V_{CEM} \leq 1700\text{V}$		2700		A

Diode Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Diode Forward Voltage	$I_F=650\text{A}, V_{GE}=0\text{V}, T_j=25^{\circ}\text{C}$		1.80	2.25	V
		$I_F=650\text{A}, V_{GE}=0\text{V}, T_j=125^{\circ}\text{C}$		1.95		
		$I_F=650\text{A}, V_{GE}=0\text{V}, T_j=150^{\circ}\text{C}$		1.90		
Q_r	Recovered Charge	$V_R=900\text{V}, I_F=650\text{A},$ $-di/dt=5200\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=25^{\circ}\text{C}$		160		μC
I_{RM}	Peak Reverse Recovery Current			695		A
E_{rec}	Reverse Recovery Energy			76.1		mJ
Q_r	Recovered Charge	$V_R=900\text{V}, I_F=650\text{A},$ $-di/dt=5200\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=125^{\circ}\text{C}$		265		μC
I_{RM}	Peak Reverse Recovery Current			760		A
E_{rec}	Reverse Recovery Energy			134		mJ
Q_r	Recovered Charge	$V_R=900\text{V}, I_F=650\text{A},$ $-di/dt=5200\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=150^{\circ}\text{C}$		310		μC
I_{RM}	Peak Reverse Recovery Current			805		A
E_{rec}	Reverse Recovery Energy			161		mJ

NTC Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
R_{25}	Rated Resistance			5.0		$\text{k}\Omega$
$\Delta R/R$	Deviation of R_{100}	$T_C=100^{\circ}\text{C}, R_{100}=493.3\Omega$	-5		5	%
P_{25}	Power Dissipation				20.0	mW
$B_{25/50}$	B-value	$R_2=R_{25}\exp[B_{25/50}(1/T_2-1/(298.15\text{K}))]$		3375		K
$B_{25/80}$	B-value	$R_2=R_{25}\exp[B_{25/80}(1/T_2-1/(298.15\text{K}))]$		3411		K
$B_{25/100}$	B-value	$R_2=R_{25}\exp[B_{25/100}(1/T_2-1/(298.15\text{K}))]$		3433		K

Module Characteristics $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Unit
L_{CE}	Stray Inductance		18		nH
$R_{CC'+EE'}$	Module Lead Resistance, Terminal to Chip		0.30		m Ω
R_{thJC}	Junction-to-Case (per IGBT) Junction-to-Case (per Diode)			34.9 69.4	K/kW
R_{thCH}	Case-to-Heatsink (per IGBT) Case-to-Heatsink (per Diode) Case-to-Heatsink (per Module)		13.5 26.9 4.5		K/kW
M	Terminal Connection Torque, Screw M4 Terminal Connection Torque, Screw M8 Mounting Torque, Screw M5	1.8 8.0 3.0		2.1 10.0 6.0	N.m
G	Weight of Module		810		g

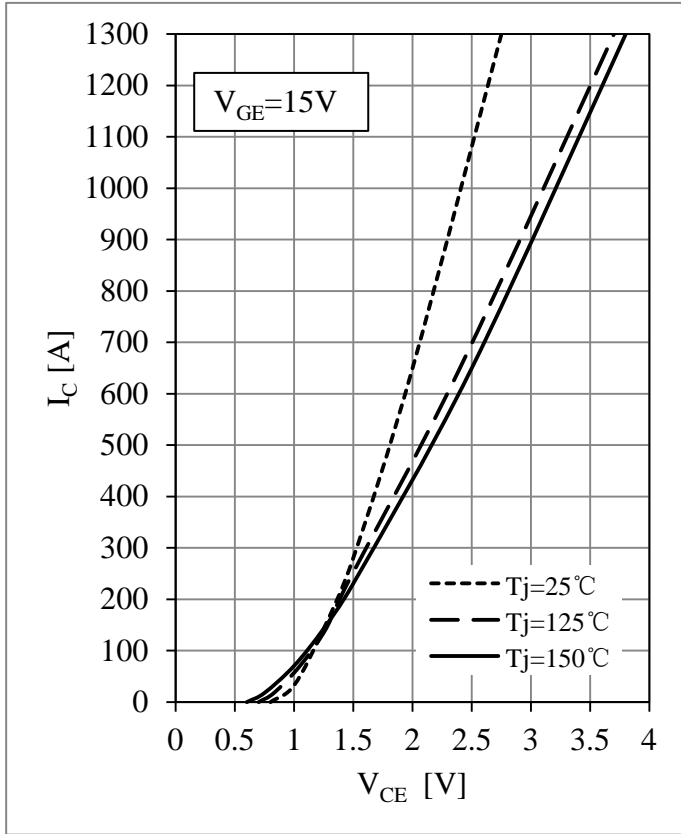


Fig 1. IGBT Output Characteristics

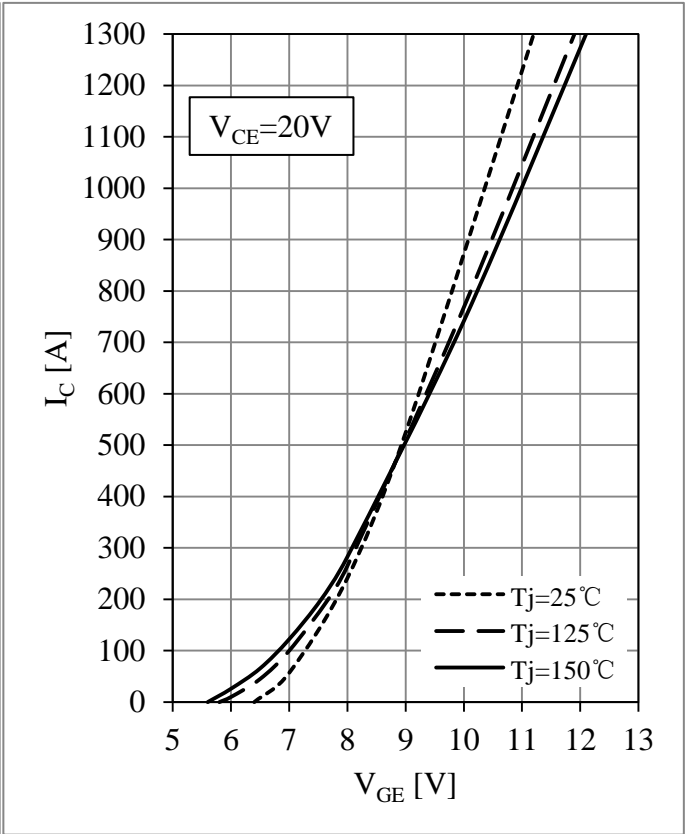


Fig 2. IGBT Transfer Characteristics

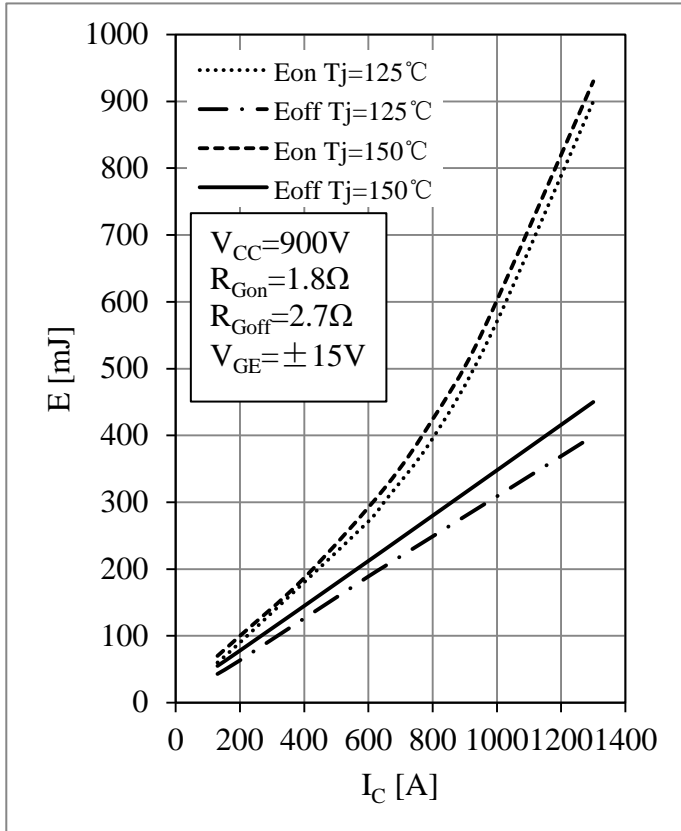


Fig 3. IGBT Switching Loss vs. I_C

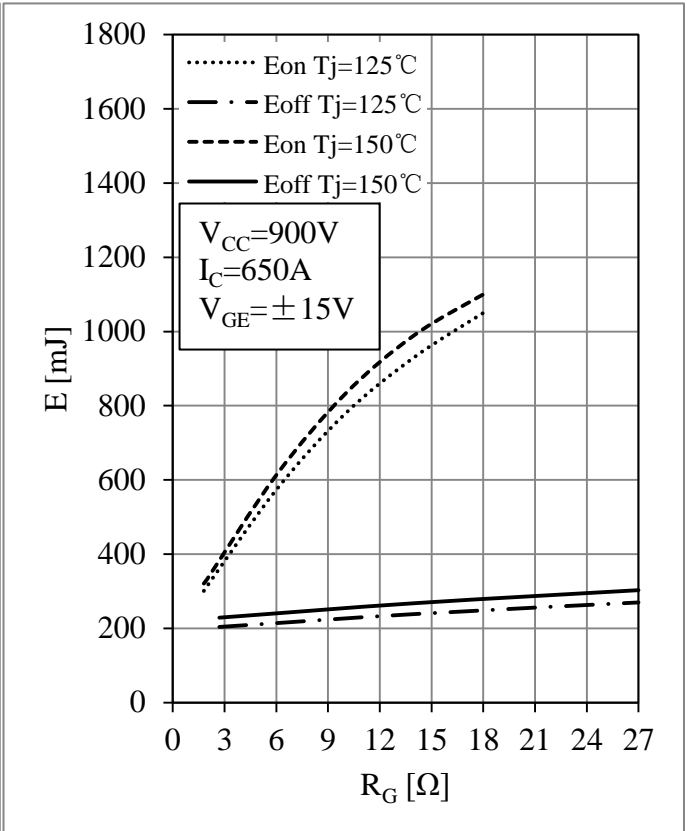


Fig 4. IGBT Switching Loss vs. R_G

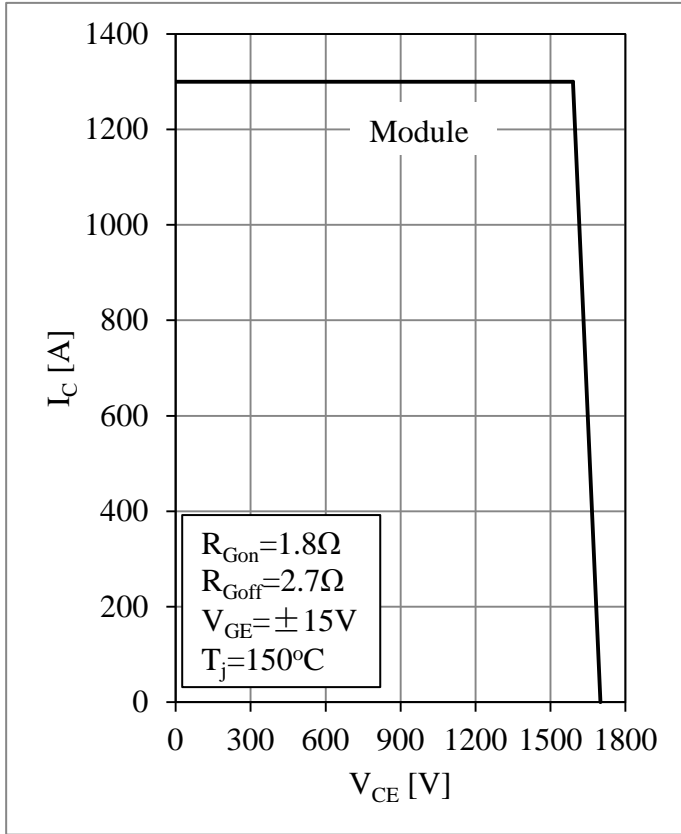


Fig 5. RBSOA

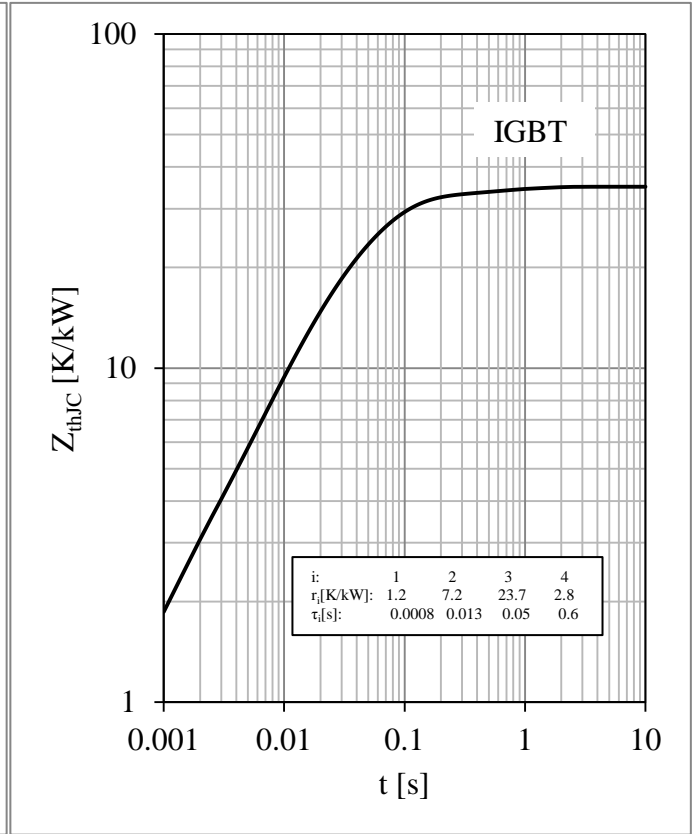


Fig 6. IGBT Transient Thermal Impedance

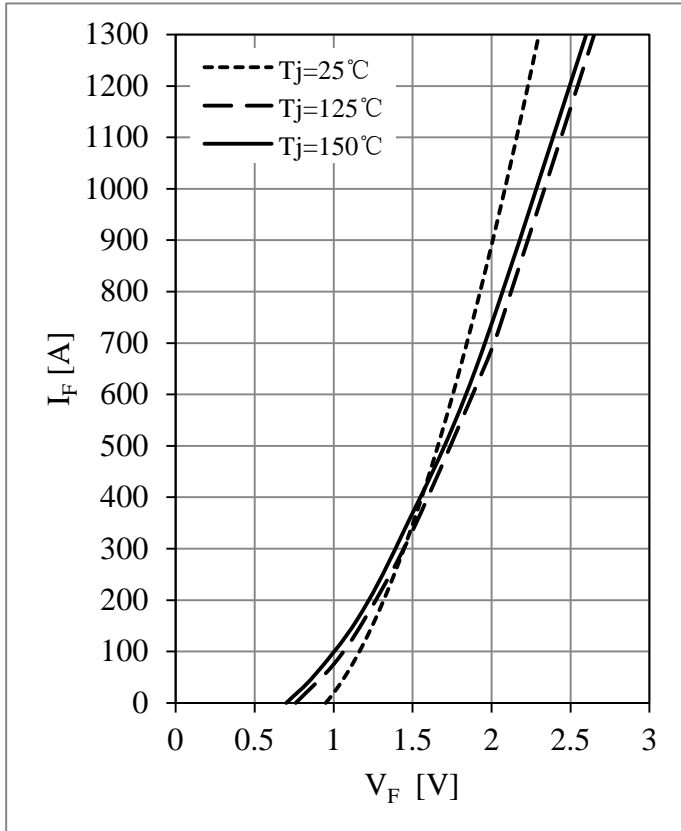


Fig 7. Diode Forward Characteristics

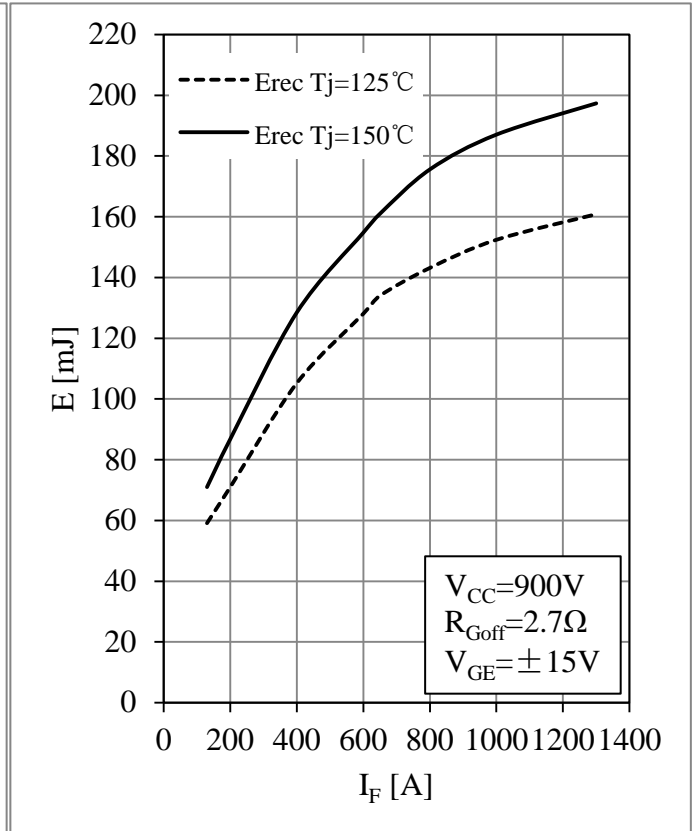


Fig 8. Diode Switching Loss vs. I_F

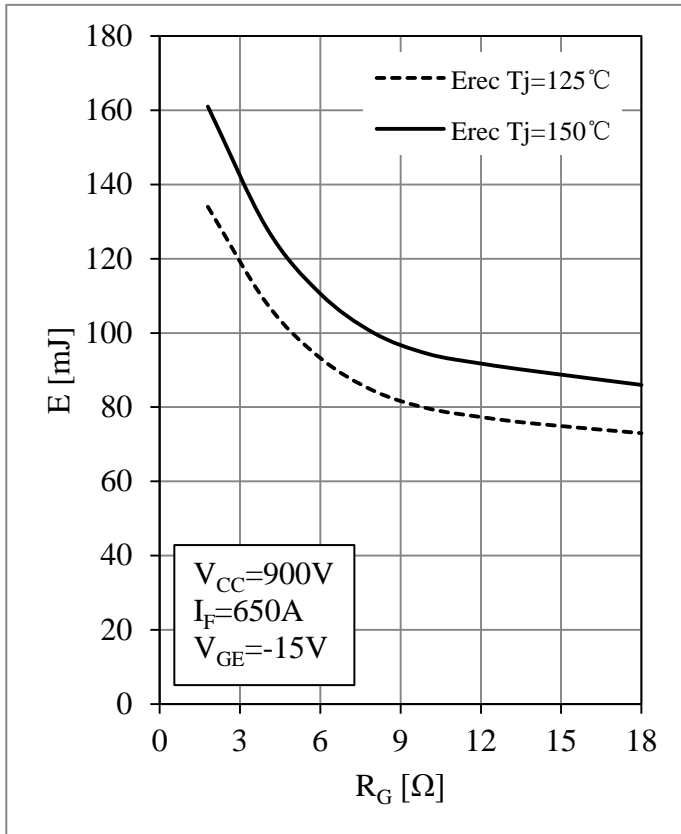


Fig 9. Diode Switching Loss vs. R_G

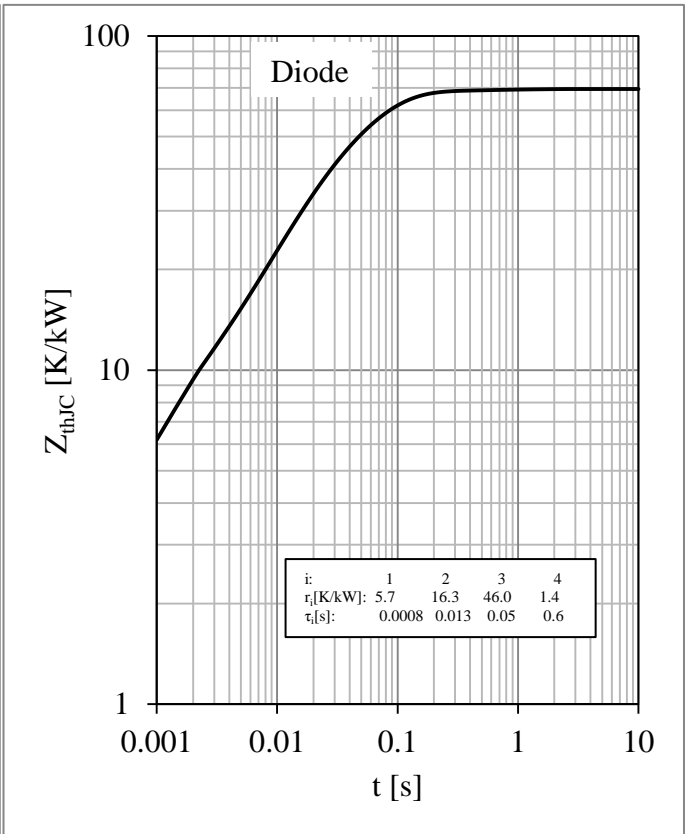


Fig 10. Diode Transient Thermal Impedance

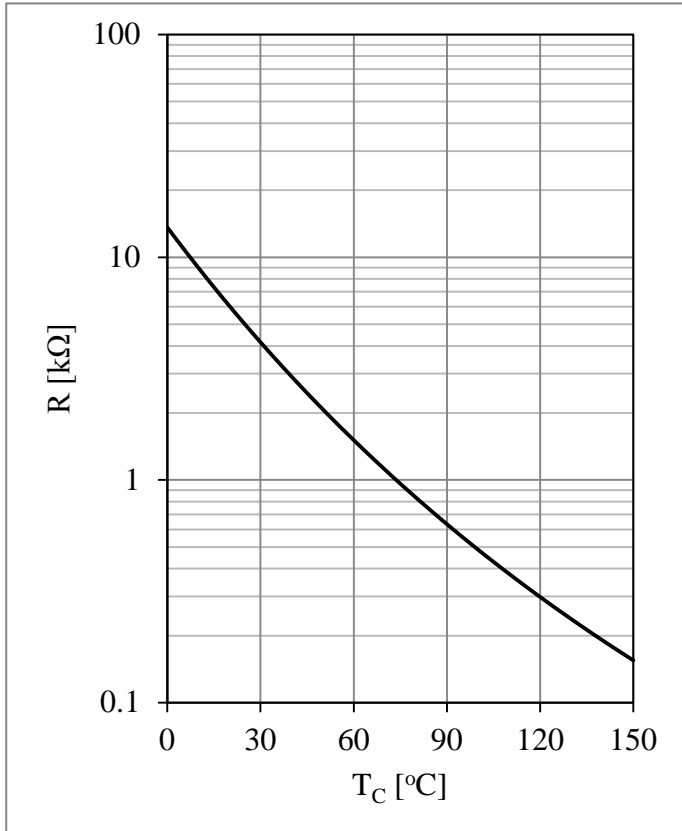
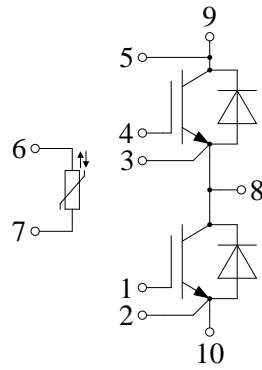


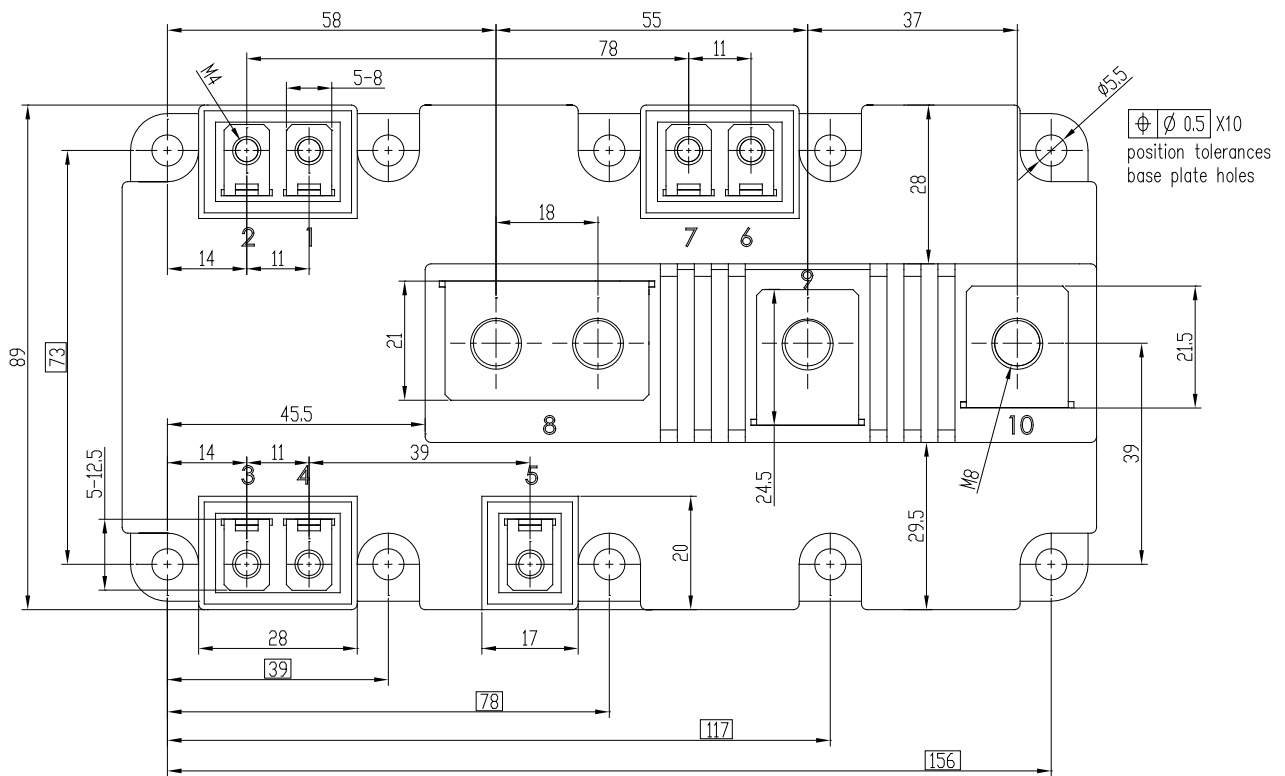
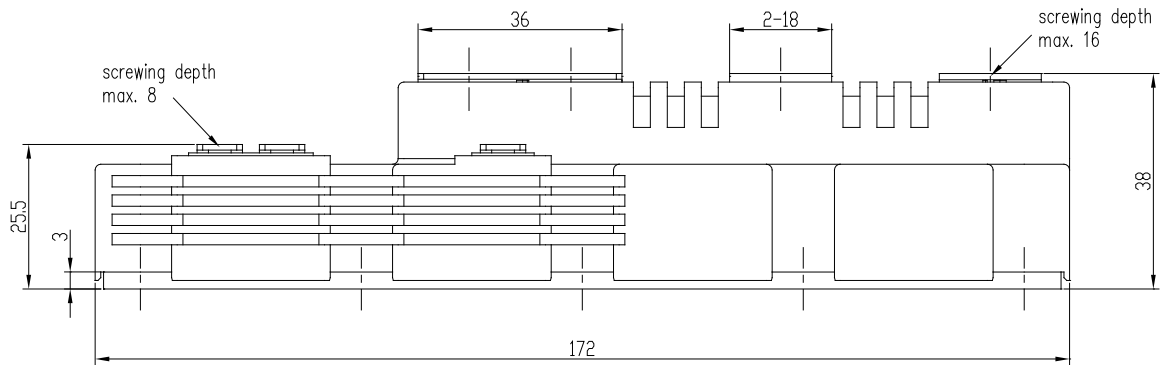
Fig 11. NTC Temperature Characteristic

Circuit Schematic



Package Dimensions

Dimensions in Millimeters



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